

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G474CBT3 STM32G474CBT3TR	745B*469XXX	A	998Z	23-08-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	183.93	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7	48	L bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	745B*469XXXX				6000001.0	1000003.1
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	15.195	mg	Supplier	die	Silicon (Si)	7440-21-3		14.607	mg	961303	79416
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	1843	152
				Supplier	metallization	Copper (Cu)	7440-50-8		0.249	mg	16387	1354
				Supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	66	5
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.081	mg	5331	440
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	197	16
				Supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	132	11
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.063	mg	4146	343
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	10596	875
Glue epoxy (3230)	M-011 Other inorganic materials	0.884	mg	Supplier	Metals	Silver	7440-22-4		0.721	mg	815000	3918
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))t	39817-09-9		0.027	mg	30000	144
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.027	mg	30000	144
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.027	mg	30000	144
				Supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.027	mg	30000	144
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.027	mg	30000	144
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.027	mg	30000	144
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.004	mg	5000	24
Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	110.513	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.321	mg	21000	12618
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.321	mg	21000	12618
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.189	mg	56000	33647
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		86.250	mg	780450	468929
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		12.744	mg	115320	69289
				Supplier	Non-metals	Carbon Black	1333-86-4		0.688	mg	6230	3743
Bonding Wire (Au)	Bonding Wire	0.263	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.260	mg	990000	1414
				Supplier	Non-metals	Other	Proprietary		0.003	mg	10000	14
				Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	5863
External plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	5863
				Supplier	Metals	Copper (Cu)	7440-50-8		54.457	mg	972499	296076
				Supplier	Metals	Iron (Fe)	7439-89-6		1.266	mg	22601	6881
				Supplier	Metals	Zinc (Zn)	7440-66-6		0.084	mg	1500	457
Leadframe_C194+Ag_HDS	Copper & its alloys	55.997	mg	Supplier	Metals	Phosphorus (Ph)	7723-14-0		0.017	mg	300	91
				Supplier	Metals	Silver (Ag)	7440-22-4		0.174	mg	3100	944
				Supplier	Metals							